

IN THE ABSTRACT

Please replace the Abstract with the following:

In one aspect, the present invention relates to an integrated circuit package includes a semiconductor die electrically connected to a substrate, a heat sink having a top and a side portion, the heat sink further including an extending finger when viewed from a top of the package, the extending finger including the side portion of the heat sink, a thermally conductive element thermally coupled with an interposed between both the semiconductor die and the heat sink, wherein the thermally conductive element does not directly contact the semiconductor die, and an encapsulant material encapsulating the thermally conductive element and the heat sink such that the top portion and the side portion of the heat sink are exposed to the surroundings of the package.